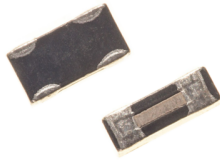


SCCM Series



Features

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission.

Applications

MIPI, MHL serial interface in mobile device.

Product Identification

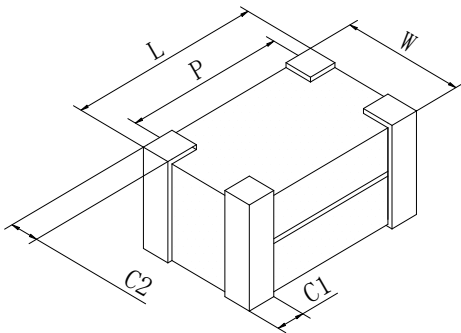
SCCM XXXXXX TL - XXX
For example:SCCM201210TL-900

General Specifications

Test Frequency.....100MHz
Parameters Test Temp..... 25℃
Operation Temp.....-20℃ to +85℃
(Including temperature Rise)
Storage Temp.....0~40℃
Storage Humidity.....<70% RH
Resistance to Soldering Heat.....260℃ for 10 sec
Temperature Rise.....40℃ Typ. at Rated Current

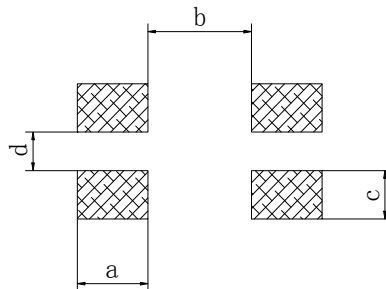
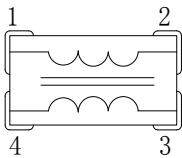
Shape And Dimensions

Dimensions In mm



TYPE	L	W	T	P	C1	C2	a	b	c	d
	±0.2	±0.2	±0.1	±0.2	±0.2	±0.2	Ref	Ref	Ref	Ref
201210	2.00	1.25	1.00	1.60	0.40	0.30	0.75	1.10	0.50	0.40

Electrical Schematic & PAD Layout



Standard Specifications

Stamp	Impedance (Ω)±25%	Test Frequency (MHz)	DCR (Ω)Max	Rated Current (mA) Max	Rated Voltage (V)	Withstand Voltage (V)	Insulation Resistance Min.(MΩ)
SCCM201210TL-670	67	100	0.40	400	10	25	200
SCCM201210TL-900	90	100	0.40	400	10	25	200
SCCM201210TL-121	120	100	0.40	400	10	25	200
SCCM201210TL-161	160	100	0.50	400	10	25	200
SCCM201210TL-181	180	100	0.50	400	10	25	200
SCCM201210TL-221	220	100	0.50	300	10	25	200

